KMY

Last update: 2013.12.1 No.RCC-K-HTS-0001-4 (Uncontrolled copy)

# Specification

(Reference)

Title: FIXED THICK FILM CHIP RESISTORS;

RECTANGULAR TYPE AND LOW OHM

Style: RCC06,10,16,20,32

## **RoHS COMPLIANCE ITEM**

Product specification contained in this specification are subject to change at any time without notice

If you have any questions or a Purchasing Specification for any quality Agreement is necessary, please contact our sales staff.



Issue Dept.: Research & Development Department Hokkaido Research Center

Drawing No: RCC-K-HTS-0001

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND LOW OHM

RCC06,10,16,20,32 Page: 1/12

## 1. Scope

1.1 This specification covers the detail requirements for fixed thick film chip resistors; rectangular type and low ohm, style of RCC06,10,16,20,32.

## 1.2 Applicable documents

JIS C 5201-1: 1998, JIS C 5201-8: 1998, JIS C 5201-8-1: 1998

IEC60115-1: 1999, IEC60115-8: 1989 Amendment 1: 1992, IEC60115-8-1: 1989

EIAJ RC-2134B-2002

## 2. Classification

Type designation shall be the following form.

- 1 Fixed thick film chip resistors; rectangular type and low ohm \_\_\_\_\_Style
- 2 Size
- 3 Rated resistance Rated resistance and symbol shall be in accordance with Sub-clause 3.2.
- 4 Tolerance on rated resistance
- 5 Packaging form

## 3. Rating

3.1 The ratings shall be in accordance with Table-1.

Table-1

	Table 1						
Style	Rated dissipation (W)	Rated current range (A)	Temperature coefficient of resistance (10 <sup>-6</sup> / °C)	Rated resistance range( $\Omega$ )	Tolerance on rated resistance		
RCC06	0.1	1.0~2.23	0~+500	0.02~0.1	J(±5%)		
RCC10	0.125	1.11~2.23	±150	0.051~0.1	E/±10/\ I/±50/\		
RCC10	0.125	1.11~2.23	0~+350	0.025~0.05	F(±1%), J(±5%)		
			±150	0.051~0.1			
RCC16	0.25	1.58~5.0	0~+250	0.033~0.05	$F(\pm 1\%), J(\pm 5\%)$		
			0~+350	0.01~0.03			
			±100	0.051~0.1			
RCC20	0.33	1.81~5.74	±150	0.03~0.05	F(±1%), J(±5%)		
			0~+250	0.01~0.027			
DCC22	0.5	2.22 5.0	±100	0.036~0.1	E/±10/\ I/±50/\		
RCC32	0.5	2.23~5.0	0~+250	0.02~0.033	F(±1%), J(±5%)		

Style	Isolation voltage (V)	Category temperature range (°C)
RCC06	50	
RCC10	100	
RCC16	100	<i>–</i> 55~+125
RCC20	500	
RCC32	300	

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND LOW OHM

RCC06,10,16,20,32 Page: 2/12

#### 3.2 Rated resistance

The rated resistance shall be in accordance with Table-2

Table-2

	Rated resistance			Rated resistance			Rated resistance		
$[m\Omega]$	Symbol	Marking symbol	$[m\Omega]$	Symbol	Marking symbol	$[m\Omega]$	Symbol	Marking symbol	
10	R010	010	39	R039	039	68	R068	068	
15	R015	015	40	R040	040	70	R070	070	
20	R020	020	43	R043	043	75	R075	075	
22	R022	022	47	R047	047	80	R080	080	
24	R024	024	50	R050	050	82	R082	082	
25	R025	025	51	R051	051	90	R090	<b>■</b> 90	
27	R027	027	56	R056	056	91	R091	091	
30	R030	030	60	R060	060	100	R100	R10	
33	R033	033	62	R062	062				
36	R036	036	65	R065	065				

## 3.3 Climatic category

55/125/56 Lower category temperature –55 °C

Upper category temperature +125 °C

Duration of the damp heat, steady state test 56days

## 3.4 Stability class

5% Limits for change of resistance:

-for long–term tests  $\pm 5\%$ -for short–term tests  $\pm 1\%$ 

## 3.5 Derating

The derated values of dissipation at temperature in excess of 70 °C shall be as indicated by the following curve.

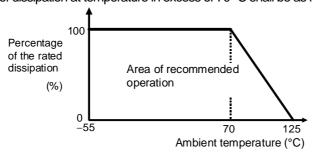


Figure-1 Derating curve

## 3.6 Rated voltage

d.c. or a.c. r.m.s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

E: Rated voltage (V)
P: Rated dissipation (W)
R: Rated resistance (
$$\Omega$$
)

## 3.7 Rated current

The rated current calculated from the square root of the quotient of the rated resistance and the rated dissipation.

The rated current shall be corresponding to rated voltage.

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND LOW OHM

RCC06,10,16,20,32 Page: 3/12

## 4. Packaging form

The standard packaging form shall be in accordance with Table-3.

Table-3

Symbol	Pac	kaging form	Standard packaging quantity / units	Application
В	Bulk (loose package)		1,000 pcs.	RCC06,10,16,20,32
PA	Press pocket taping (paper taping)	8mm width, 2mm pitches	15,000 pcs.	RCC06
TH	Paper taping	8mm width, 2mm pitches	10,000 pcs.	RCC10
TP	Paper taping 8mm width, 4mm pitches		5,000 pcs.	RCC16, 20, 32

## 5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-4.

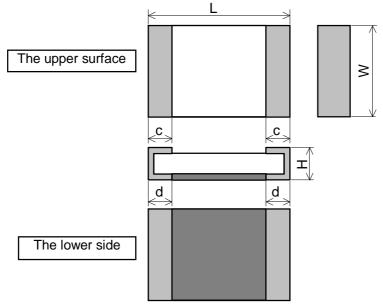


Figure-2

Table-4 Unit: mm

Style	Rated resistance range	L	W	Н	С	d
RCC06	All resistance range	0.6±0.03	0.3±0.03	0.23 +0.03	0.15 <sup>+0.05</sup> <sub>-0.10</sub>	0.15±0.05
RCC10	All resistance range	1.0±0.05	0.5±0.05	0.35 +0.05	0.25 +0.05 +0.10	0.25 +0.05 -0.10
RCC16	20mΩ≤R	4.010.4	0.0 ±0.15	0.5±0.1	0.3±0.1	0.3±0.1
	R<20mΩ	1.6±0.1	0.8 +0.15 -0.05			0.55±0.10
RCC20	20mΩ≤R	2040.15	1.25±0.10	0.6±0.1	0.4+0.2	0.4±0.2
NCC20	R<20mΩ 2.0±0.15		1.25±0.10	0.0±0.1	0.4±0.2	0.6±0.2
RCC32	All resistance range	3.1±0.2	1.6±0.15	0.6±0.1	0.5±0.25	0.5±0.25

## 5.2 Net weight (Reference)

Style	Net weight (mg)			
RCC06	0.16			
RCC10	0.6			
RCC16	2			
RCC20	5			
RCC32	9			

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND LOW OHM

RCC06,10,16,20,32 Page: 4/12

## 6. Marking

The rated resistance of marking symbol of Sub-clause 3.2 shall be marked on substrate side.

The Rated resistance of RCC06, RCC10 and RCC16 should not be marked.

(Example) "050"  $\rightarrow$  0.05 [ $\Omega$ ]  $\rightarrow$  50m $\Omega$  (Application: 10m $\Omega$  $\rightarrow$ 91m $\Omega$ )

"■90"  $\rightarrow$  0.09 [ $\Omega$ ]  $\rightarrow$  90m $\Omega$  (Application: 90m $\Omega$  only)

"R10"  $\rightarrow$  0.1 [ $\Omega$ ]  $\rightarrow$  100m $\Omega$  (Application: 100m $\Omega$  or above

#### 7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201–1: 1998.

7.2 The performance shall be satisfied in Table-5.

Table-5(1)

No.	Test items	Condition of test (JIS C 5201–1)	Performance requirements
1	Visual examination	Sub-clause 4.4.1 Checked by visual examination.	As in 4.4.1 The marking shall be legible, as checked by visual examination.
2	Dimension	Sub-clause 4.4.2	As specified in Table-4 of this specification.
	Resistance	Sub-clause 4.5 Measurement current: 1(A) Note: The measuring apparatus corresponding to DC Low-ohm Mater (1A) of AX-1152D for ADEX CORPORATION.	As in 4.5.2  The resistance value shall correspond with the rated resistance taking into account the specified tolerance.
3	Voltage proof	Sub-clause 4.7 Method: 4.6.1.4(See Figure-5) Test voltage: Alternating voltage with a peak value of 1.42 times the insulation voltage. Duration: 60 s±5 s Insulation resistance Test voltage: Insulation voltage Duration: 1 min.	No breakdown or flash over $R \geq 1  G\Omega$
4	Solderability	Sub-clause 4.17 Without aging Flux: The resistors shall be immersed in a non-activated soldering flux for 2 s. Bath temperature: 235 °C±5 °C Immersion time: 2 s±0.5 s	As in 4.17.4.5 The terminations shall be covered with a smooth and bright solder coating.
5	Mounting  Overload (in the mounted state)  Solvent resistance of the marking	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3 Sub-clause 4.13 The applied voltage shall be 2.5 times the rated voltage or the current corresponding to. Duration: 2 s Visual examination Resistance Sub-clause 4.30 Solvent: 2-propanol Solvent temperature: 23 °C±5 °C Method 1	No visible damage ΔR ≤ ±1% Legible marking
		Rubbing material: cotton wool Without recovery	

**KMY** 

Drawing No: RCC-K-HTS-0001

/4

FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND LOW OHM Title:

RCC06,10,16,20,32 Page: 5/12

## Table-5(2)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
6	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure-4	
	Bound strength of the end	Sub-clause 4.33	
	face plating	Bent value: 3 mm	.5. 404
	Final managements	Resistance	ΔR ≤ ±1%
	Final measurements	Sub-clause 4.33.6	No. 3-7 to decree
		Visual examination	No visible damage
7	Resistance to soldering heat	Sub-clause 4.18 (JEITA RC-2144 2.3.2)	
		T <sub>1</sub> :Pre-heat minimum temp.:150±5 °C	
		T <sub>2</sub> :Pre-heat maximum temp.:180±5 °C	
		T <sub>3</sub> :Soldering temp.:220 °C	
		T <sub>4</sub> :Peak temp.:250 °C	
		t <sub>1</sub> :Pre-heat duration:120±5 s	
		t <sub>2</sub> :Soldering duration:60 to 90 s	
		t <sub>3</sub> :Peak duration(T <sub>4</sub> -5°C):20 to 40 s Pre-reflow soldering: 1 time	
		(Initial measurements)	
		Reflow soldering: 3 times	
		t <sub>3</sub>	
		T <sub>4</sub>	
		/	
		T <sub>3</sub>	
		T <sub>2</sub>	
		T <sub>1</sub> t <sub>1</sub>	
		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
	0	Visual examination	No visible damage
	Component solvent resistance	1 1 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	ΔR ≤ ±1%
	resistative	Sub-clause 4.29	
		Solvent: 2–propanol	
		Solvent temperature: 23 °C±5 °C Method 2	
		Recovery: 48 h Visual examination	No visible damage
		Resistance	$\Delta R \le \pm 1\%$
1		1 /COIDIGI IUC	△11 → 1 /0

**KMY** 

Drawing No: RCC-K-HTS-0001

/4

FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND LOW OHM Title:

RCC06,10,16,20,32 Page: 6/12

Table-5(3)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
8	Mounting	Sub-clause 4.31	
	iviouriting	Substrate material: Epoxide woven glass	
	Adhesion	Test substrate: Figure–3	
	Adriesion	Sub-clause 4.32	
		Force: 5 N (RCC06: 3N)	
		Duration: 10 s±1 s	NI - Pathila da sa sa
	Dan'd alaman (a ann ann)	Visual examination	No visible damage
	Rapid change temperature	Sub-clause 4.19	
		Lower category temperature: -55 °C	
		Upper category temperature: +125 °C	
		Duration of exposure at each temperature: 30	
		min.	
		Number of cycles: 5 cycles.	
		Visual examination	No visible damage
		Resistance	ΔR ≤ ±1%
9	Climatic sequence	Sub-clause 4.23	
9	-Dry heat		
	-Dry neat	Sub-clause 4.23.2	
		Test temperature: +125 °C	
		Duration: 16 h	
	-Damp heat, cycle	Sub-clause 4.23.3	
	(12+12hour cycle)	Test method: 2	
	First cycle	Test temperature: 55 °C	
		[Severity(2)]	
	-Cold	Sub-clause 4.23.4	
		Test temperature –55 °C	
		Duration: 2h	
	-Damp heat, cycle	Sub-clause 4.23.6	
	(12+12hour cycle)	Test method: 2	
	Remaining cycle	Test temperature: 55 °C	
		[Severity (2)]	
		Number of cycles: 5 cycles	
	–D.C. load	Sub-clause 4.23.7	
	2.0.1000	The applied current shall be the rated current.	
		Duration: 1 min.	
		Visual examination	No visible damage
		Resistance	ΔR ≤ ±5 %
10	Mounting		
10		Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
	Endurance at 70 °C	Test substrate: Figure–3	
	Endulance at 70 °C	Sub-clause 4.25.1	
		Ambient temperature: 70 °C±2 °C	
		Duration: 1000 h	
		The current shall be applied in cycles of 1.5 h	
		on and 0.5 h.	
		The applied current shall be the rated current	
		Examination at 48 h, 500 h and	
		1000 h:	
		Visual examination	No visible damage
		Resistance	ΔR ≤ ±5 %

**KMY** Drawing No: RCC-K-HTS-0001

FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND LOW OHM

RCC06,10,16,20,32 Page: 7/12

/4

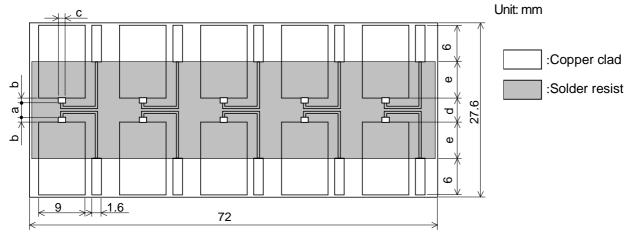
## Table-5(4)

Test items	Condition of test (JIS C 5201–1)	Performance requirements
Mounting  Variation of resistance with	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3 Sub-clause 4.8	As in Table–1
temperature	+20 °C / +125 °C	
Mounting  Damp heat, steady state	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3 Sub-clause 4.24 Ambient temperature: 40 °C±2 °C Relative humidity: 93 ½ % Without current applied. Visual examination	No visible damage Legible marking ∆R ≤ ±5%
Dimensions (detail) Mounting  Endurance at upper category temperature	Sub-clause 4.4.3 Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3 Sub-clause 4.25.3 Ambient temperature:125 °C±2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h: Visual examination	As in Table–4  No visible damage  AR < ±5%
	Mounting  Variation of resistance with temperature  Mounting  Damp heat, steady state  Dimensions (detail)  Mounting  Endurance at upper	Mounting  Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3 Sub-clause 4.8 +20 °C /+125 °C  Mounting  Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3 Sub-clause 4.24 Ambient temperature: 40 °C+2 °C Relative humidity: 93 *: 3 % Without current applied. Visual examination  Resistance  Dimensions (detail) Mounting  Sub-clause 4.4.3 Sub-clause 4.4.3 Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3 Sub-clause 4.25.3 Ambient temperature: 125 °C+2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h:

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND LOW OHM

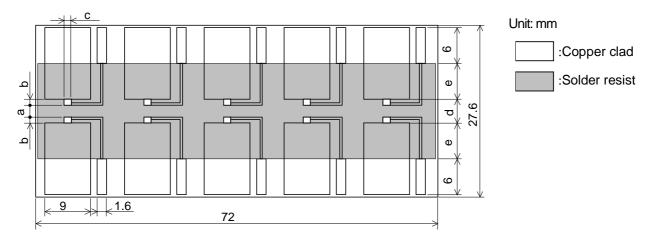
RCC06,10,16,20,32 Page: 8/12

## 8. Test substrate



Style	Rated resistance range	а	b	С	d	е
RCC16	20mΩ≤R	1.0	0.6	0.8	2.2	6.2
RCC16	R<20mΩ	0.6	8.0	0.9	2.2	0.2
RCC20	20mΩ≤R	1.3	0.7	1.25	2.7	E OE
RCC20	R<20mΩ	8.0	0.95	1.35	2.7	5.95
RCC32	CC32 All resistance range		0.9	1.7	3.9	5.35

RCC16,20,32 TEST SUBSTRATE



Style	а	b	С	d	е
RCC06	0.3	0.6	0.6	1.5	6.55
RCC10	0.6	0.5	0.7	16	65

## RCC06,10 TEST SUBSTRATE

Remark 1). Material: Epoxide woven glass

Thickness: 1.6mm Thickness of copper clad: 0.035mm

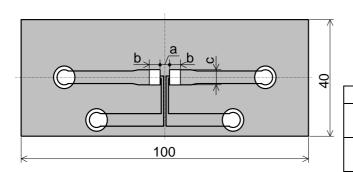
2). In the case of connection by connector, the connecting terminals are gold plated. However, the plating is not necessary when the connection is made by soldering.

Figure-3

**KMY** Drawing No: RCC-K-HTS-0001

FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND LOW OHM

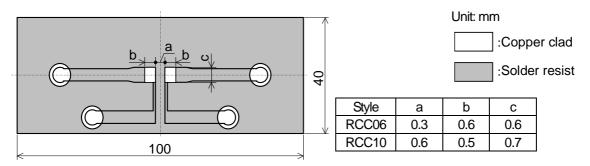
RCC06,10,16,20,32 Page: 9/12



Onit: mm				
:Copper clad				
:Solder resist				
Style	Rated resistance range	а	b	С
RCC16	20mΩ≤R	1.0	0.6	0.8
	R<20mΩ	0.6	0.8	0.9
RCC20	20mΩ≤R	1.3	0.7	1.25
	R<20mΩ	0.8	0.95	1.35
RCC32	All resistance range	2.1	0.9	1.7

I Init: mm

## RCC16,20,32 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE



## RCC06,10 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

Remark 1). Material: Epoxide woven glass

Thickness: 1.6mm Thickness of copper clad: 0.035mm

Figure-4

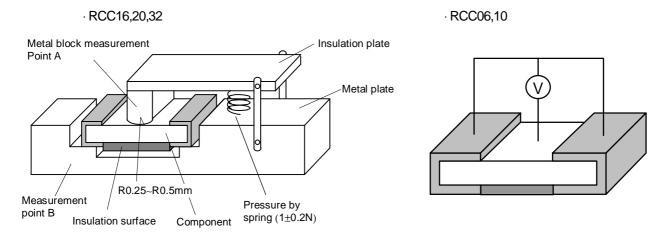


Figure-5

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND LOW OHM

RCC06,10,16,20,32 Page: 10/12

## 9. Taping

- 9.1 Applicable documents JIS C 0806-3: 1999, EIAJ ET-7103: 2004, EIAJ ET-7200B: 2003
- 9.2 Taping dimensions
- 9.2.1 Press pocket taping (Paper taping, 8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-6 and Table-6.

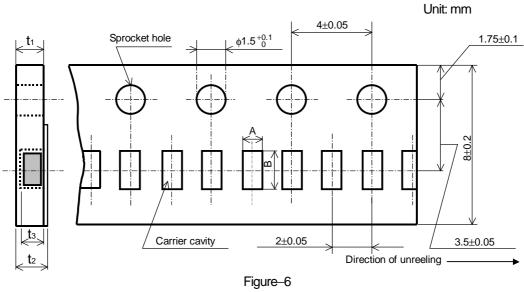


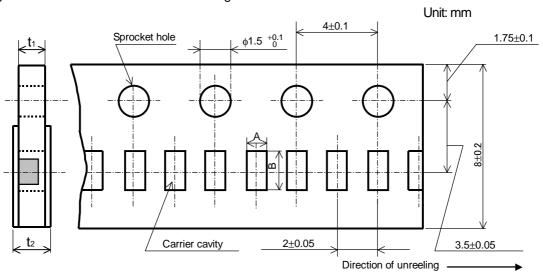
Figure-6
Table-6 Unit: mm

Style A B t<sub>1</sub> t<sub>2</sub> t<sub>3</sub>

RCC06 0.37±0.05 0.67±0.05 0.42±0.03 0.45±0.05 0.27±0.02

## 9.2.2 Paper taping (8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-7 and Table-7.



Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND LOW OHM

RCC06,10,16,20,32 Page: 11/12

### 9.2.3 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-8 and Table-8.

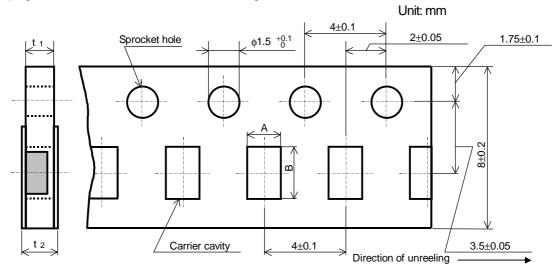
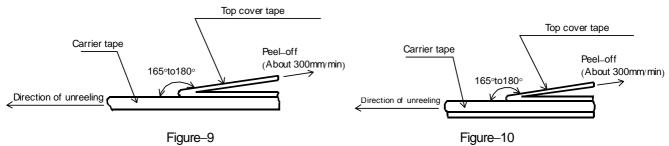


Figure-8 Table-8 Unit: mm Style Α В t<sub>1</sub> t<sub>2</sub> RCC16  $1.9 \pm 0.2$ 1.15±0.15  $0.6 \pm 0.1$ 0.8max. RCC20 1.65±0.15  $2.5 \pm 0.2$  $0.8 \pm 0.1$ 1.0max. RCC32 2.00±0.15  $3.6 \pm 0.2$ 

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following RCC06, 10: Figure–9, RCC16,20,32: Figure–10.
- 6). When the tape is bent with the minimum radius for 25mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.
- The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The resistors shall be faced to upward at the substrate side in the carrier cavity.

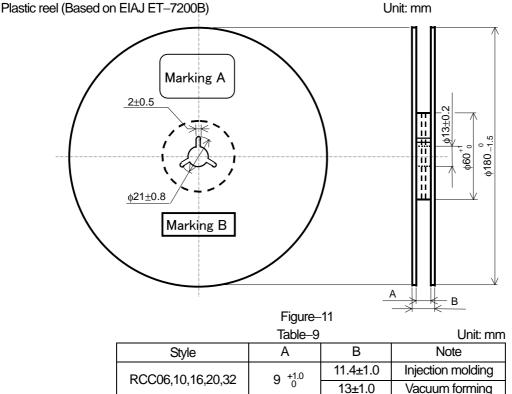


Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND LOW OHM

RCC06,10,16,20,32 Page: 12/12

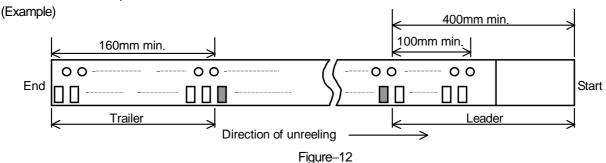
#### 9.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–11 and Table–9.



Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

## 9.4 Leader and trailer tape.



## 10. Marking on package

The label of a minimum package shall be legibly marked with follows.

## 10.1 Marking A

- (1) Classification (Style, Rated resistance, Tolerance on rated resistance, Packaging form) (2) Quantity
- (3) Lot number (4) Manufacturer's name or trade mark (5) Others
- 10.2 Marking B (KAMAYA control label)